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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/735,097	12/11/2000	John J. Weisgerber	GSIL0148 PUS	5342
22045	7590	12/10/2004	EXAMINER	
BROOKS KUSHMAN P.C. 1000 TOWN CENTER TWENTY-SECOND FLOOR SOUTHFIELD, MI 48075			KIBLER, VIRGINIA M	
		ART UNIT	PAPER NUMBER	
			2623	

DATE MAILED: 12/10/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	09/735,097	WEISGERBER ET AL.
	Examiner	Art Unit
	Virginia M Kibler	2623

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 13 September 2004.
 2a) This action is FINAL. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-7,10-17,20 and 22-28 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 1-7,10-17,20 and 22-28 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) <input type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413)
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Date. _____
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____	5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
	6) <input type="checkbox"/> Other: _____

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 9/13/04 has been entered.

Response to Amendment

2. The amendment received on 9/13/04 has been entered. Claims 1-7, 10-17, 20, and 22-28 remain pending.

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 1, 2, 11, 12, 26, and 27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mengel ("Automated Inspection of Solder Joints on PC Boards by Supplementary

Processing of 3D and Gray-level Images") in view of Juha et al. ("The Use of 3-D Imaging for the Inspection of Hybrid/SMT Circuits").

Regarding claim 1, Mengel discloses imaging the components and the mounting substance on the PCB to obtain 3D and 2D data associated with the component and material surrounding the component (Page 787, Col. 2, Para. 1), and processing the 3D and 2D data in combination to find the a position of the component as a function of 3D and 2D data and based on component features as differentiated from the mounting substance or the circuit board on which the component is placed (Pages 788-789, in particular Figures 2 & 4-7). Mengel discloses obtaining 2D and 3D data associated with the component and material surrounding the component (Page 789; Figure 7), combining the 2D and 3D data to identify a set of data which corresponds to an overlapping image region of the 2D and 3D data, and locating a component feature using at least a portion of the set of data (Page 789).

Mengel discloses processing the 3D and 2D data to differentiate the component and material surrounding the component (Pages 788-789, in particular Figures 2 & 4-7), but does not appear to explicitly state thresholding the data. However, this limitation is well known in the art as evidenced by Juha et al. ("Juha"). Juha discloses thresholding at least a portion of each of the 2D and 3D data to obtain respective 2D and 3D threshold data associated with a component and material surrounding the component (Figure 2). Mengel and Juha are combinable because they are from the same field of endeavor of circuit inspection. At the time of the invention it would have been obvious to one of ordinary skill in the art to have modified the processing of 2D and 3D data disclosed by Mengel to specify thresholding. The motivation for doing so would have been because thresholding is a well known methodology routinely utilized in the art of image

processing and provides a method of differentiating the component and material surrounding the component. Therefore, it would have been obvious to combine Mengel with Juha to obtain the invention as specified in claim 1.

Regarding claim 2, Mengel discloses the mounting substance as solder paste (Abstract, lines 6-9).

Regarding claims 11 and 12, the arguments analogous to those presented above for claims 1 and 2 are applicable to claims 11 and 12, respectively.

Regarding claim 26, Mengel discloses comparing at least one of a predetermined 3D size and shape of a component with 3D data representative of the component so as to verify component presence (Pages 788-790).

Regarding claim 27, Mengel discloses comparing at least one of a predetermined 3D size and shape of an attribute of the component with 3D data representative of the attribute to verify component presence (Pages 788-490).

5. Claims 5, 15, 22-25, and 28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mengel ("Automated Inspection of Solder Joints on PC Boards by Supplementary Processing of 3D and Gray-level Images") in view of Juha et al. ("The Use of 3-D Imaging for the Inspection of Hybrid/SMT Circuits") as applied to claims 1 and 11 above, and further in view of Montillo et al. (US 6,526,165).

Regarding claims 5 and 15, Mengel and Juha do not appear to recognize calculating the centroids of the feet of the leads. However, Montillo et al. ("Montillo") teaches that it is known to calculate the centroids of the feet (Col. 6, lines 3-40). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have modified the inspection of

Art Unit: 2623

solder joints disclosed by Mengel and Juha to include calculating the centroids of the feet as taught by Montillo because it is well known and accurately inspects the placement of the object by properly registering the object with the pads on a PCB (Col. 1, lines 31-37).

Regarding claims 22-25 and 28, Mengel and Juha do not appear to recognize forming a blob image and masking with the blob image. However, Montillo teaches that it is known to form a blob image and perform masking with the blob image (Col. 13, lines 62-67, Col. 14, lines 1-15). Montillo teaches blob analysis which entails using an image segmentation threshold to determine both the location and orientation. Montillo further teaches detecting an edge of the blob image and applying a bounding rectangle to the edge wherein the bounding rectangle is a minimum rectangle and is used to determine component position and orientation (Col. 13, lines 62-67, Col. 14, lines 1-15; Figure 12b, element 1210). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have modified the evaluation of the component detection as disclosed by Mengel and Juha to include forming a blob image and masking as taught by Montillo because blob analysis is a standard tool for determining the center of mass, area, and bounding box of a region of connected pixels.

6. Claims 3, 4, 13, and 14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mengel (“Automated Inspection of Solder Joints on PC Boards by Supplementary Processing of 3D and gray-level Images”) in view of Juha et al. (“The Use of 3-D Imaging for the Inspection of Hybrid/SMT Circuits”) as applied to claims 1 and 11 above, and further in view of Proskey (4,159,648).

Regarding claims 3 and 13, Mengel and Juha do not appear to recognize the mounting substance as an adhesive. However, Proskey teaches that it is known to use an adhesive as a

Art Unit: 2623

mounting substance (Col. 4, lines 47-49). It would have been an obvious matter of design choice to have modified the solder paste disclosed by Mengel and Juha to an adhesive, as taught by Proskey, since applicant has not disclosed that the adhesive solves any stated problem or is for any particular purpose and it appears that the invention would perform equally well.

Regarding claims 4 and 14, the arguments analogous to those presented above for claim 3 are applicable to claims 4 and 14. Note, Proskey discloses a glue (Col. 4, lines 47-49).

7. Claims 6 and 16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mengel (“Automated Inspection of Solder Joints on PC Boards by Supplementary Processing of 3D and gray-level Images”) in view of Juha et al. (“The Use of 3-D Imaging for the Inspection of Hybrid/SMT Circuits”) as applied to claims 1 and 11 above, and further in view of Roy et al. (5,956,134).

Regarding claims 6 and 16, Mengel and Juha do not appear to recognize calculating the average height of the feet. However, Roy teaches that it is known the leads have feet and the step of processing includes the step of calculating the average height of the feet (Col. 6, lines 5-13). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have modified the inspection of electronic components disclosed by Mengel and Juha to include calculating the average height of the feet as taught by Roy because it is well known in the art and determines if the conductor leads are in a proper position with respect to each other.

8. Claims 7 and 17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mengel (“Automated Inspection of Solder Joints on PC Boards by Supplementary Processing of 3D and gray-level Images”) in view of Juha et al. (“The Use of 3-D Imaging for the Inspection of

Hybrid/SMT Circuits") as applied to claims 1 and 11 above, and further in view of Kent et al. (6,047,084).

Regarding claims 7 and 17, Mengel discloses determining the quality of solder joints using test parameters and degree of inspection including solder bridges and excess solder (Page 790). Mengel and Juha do not expressly recognize calculating a percentage of the mounting substance. However, Kent et al. ("Kent") teaches that it is known to calculate the border violation percentage of the mounting substance (Col. 12, lines 4-25). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have modified the solder joints inspection disclosed by Mengel and Juha to include calculating the border violation percentage of the mounting substance as taught by Kent because it is well known in the art and ensures physical and electrical connectivity of the solder to the pad (Col. 12, lines 23-26).

9. Claims 10 and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mengel ("Automated Inspection of Solder Joints on PC Boards by Supplementary Processing of 3D and gray-level Images") in view of Juha et al. ("The Use of 3-D Imaging for the Inspection of Hybrid/SMT Circuits") as applied to claims 1 and 11 above, and further in view of Paulsen et al. (6,522,777).

Regarding claims 10 and 20, Mengel and Juha do not appear to recognize including using upper and lower thresholds to find the locations. However, Paulsen et al. ("Paulsen") teaches that it is known to use upper and lower thresholds to find the locations (Col. 6, lines 39-47). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to have modified the comparison disclosed by Mengel (Page 788, col. 2) to include

using an upper and lower thresholds as taught by Paulsen because it is a methodology routinely implemented in the art to ensure coplanarity within a predetermined tolerance.

Response to Arguments

10. Applicant's arguments with respect to claims 1 and 11 have been considered but are moot in view of the new ground of rejection.

Contact Information

11. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Virginia M Kibler whose telephone number is (703) 306-4072. The examiner can normally be reached on Mon-Thurs 8:00 - 5:30 and every other Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Virginia Kibler can be reached on (703) 306-4072. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Art Unit: 2623

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Virginia Kbler

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12/09/04

MEHRDAD DASTOURI
PRIMARY EXAMINER

Mehrdad Dastouri